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(12) United States Patent

Chistyakov

(54) METHODS AND APPARATUS FOR GENERATING HIGH-DENSITY PLASMA

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U.S.C. 154(b) by 748 days.

This patent is subject to a terminal dis-

claimer.

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(51) Int. Cl.

C23C 14/35 (2006.01)

 $\begin{array}{ccc} C23C \ 16/00 & (2006.01) \\ (52) & \text{U.S. Cl.} & & & & & & \\ \end{array}$

See application file for complete search history.

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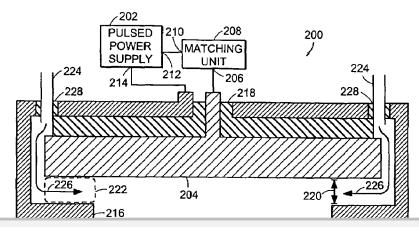
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(57) ABSTRACT

Methods and apparatus for generating a strongly-ionized plasma are described. An apparatus for generating a strongly-ionized plasma according to the present invention includes an anode and a cathode that is positioned adjacent to the anode to form a gap there between. An ionization source generates a weakly-ionized plasma proximate to the cathode. A power supply produces an electric field in the gap between the anode and the cathode. The electric field generates excited atoms in the weakly-ionized plasma and generates secondary electrons from the cathode. The secondary electrons ionize the excited atoms, thereby creating the strongly-ionized plasma.

33 Claims, 13 Drawing Sheets





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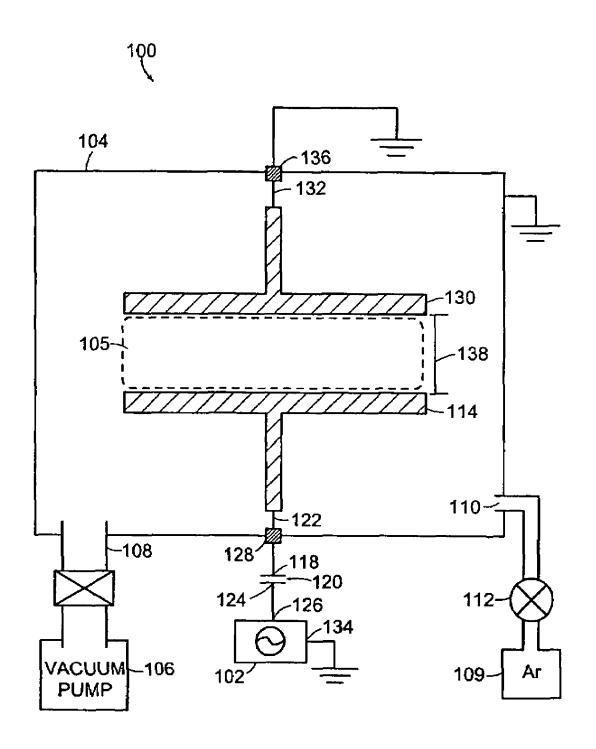


FIG. 1
PRIOR ART



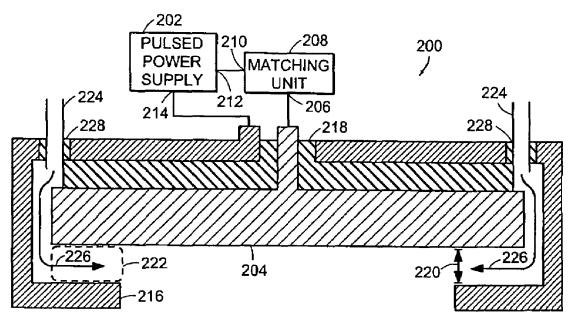


FIG. 2A

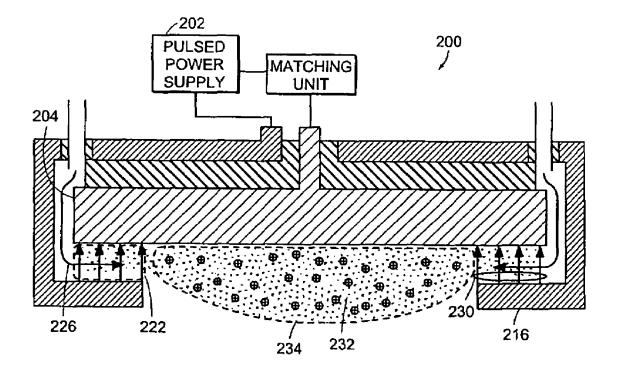


FIG. 2B



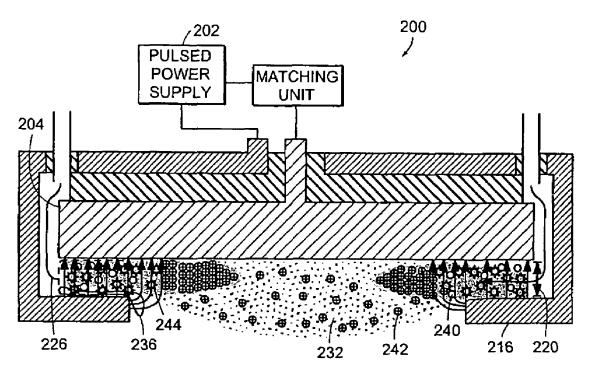


FIG. 2C

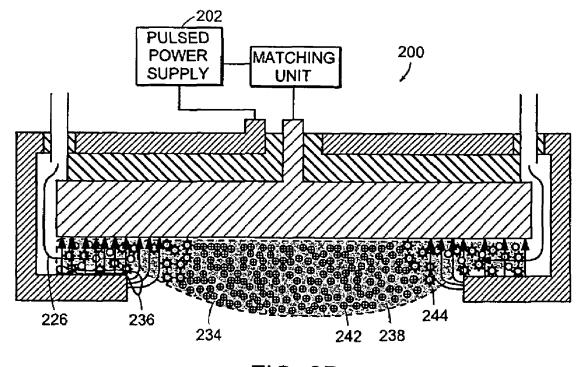


FIG. 2D



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